

MOS FIELD EFFECT TRANSISTOR

 μ PA572T

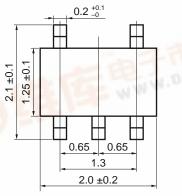
N-CHANNEL MOS FET (5-PIN 2 CIRCUITS) FOR SWITCHING

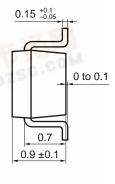
The μ PA572T is a super-mini-mold device provided with two MOS FET circuits. It achieves high-density mounting and saves mounting costs.

FEATURES

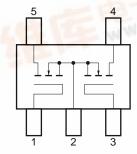
- · Two source common MOS FET circuits in package the same size as SC-70
- Directly driven by 3 V power supply
- · Automatic mounting supported

PACKAGE DIMENSIONS (in millimeters)





EQUIVALENT CIRCUIT



PIN CONNECTION

- 1. Gate 1 (G1)
- 2. Source (common) 3. Gate 2 (G2)
- 4. Drain 2 (D2)
- 5. Drain 1 (D1)
- Marking: DB

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C)

| PARAMETER | SYMBOL | TEST CONDITIONS | RATINGS | UNIT |
|-------------------------|--------------------|-------------------------------|-------------|------|
| Drain to Source Voltage | Voss | Ves = 0 | 30 | V |
| Gate to Source Voltage | Vgss | Vps = 0 | ±7 | V |
| Drain Current (DC) | I _{D(DC)} | In The second | ±100 | mA |
| Drain Current (pulse) | ID(pulse) | PW ≤ 10 ms, Duty Cycle ≤ 50 % | ±200 | mA |
| Total Power Dissipation | Рт | | 200 (Total) | mW |
| Channel Temperature | Tch | | 150 | °C |
| Operating Temperature | Topt | | -55 to +80 | °C |
| Storage Temperature | T _{stg} | | -55 to +150 | °C |

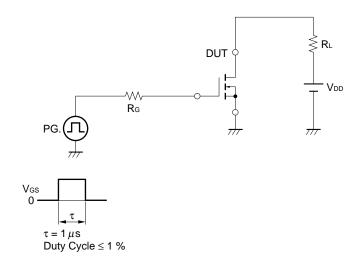


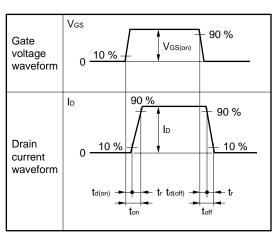


ELECTRICAL CHARACTERISTICS (TA = 25 °C)

| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|-------------------------------------|----------------------|--|------|------|------|------|
| Drain Cut-off Current | Ipss | V _{DS} = 30 V, V _{GS} = 0 | | | 1.0 | μΑ |
| Gate Leakage Current | Igss | $V_{GS} = \pm 5 \text{ V}, V_{DS} = 0$ | | | ±3.0 | μΑ |
| Gate Cut-off Voltage | V _{GS(off)} | $V_{DS} = 3 \text{ V}, \text{ ID} = 10 \mu \text{A}$ | 0.8 | 1.0 | 1.5 | V |
| Forward Transfer Admittance | yfs | V _{DS} = 3 V, I _D = 10 mA | 20 | 50 | | mS |
| Drain to Source On-State Resistance | RDS(on)1 | V _G S = 2.5 V, I _D = 1 mA | | 7 | 13 | Ω |
| Drain to Source On-State Resistance | RDS(on)2 | V _G S = 4.0 V, I _D = 10 mA | | 5 | 8 | Ω |
| Input Capacitance | Ciss | V _{DS} = 5.0 V, V _{GS} = 0, f = 1 MHz | | 16 | | pF |
| Output Capacitance | Coss | | | 14 | | pF |
| Reverse Transfer Capacitance | Crss | | | 2 | | pF |
| Turn-On Delay Time | td(on) | $V_{DD} = 5 \text{ V}, \text{ ID} = 10 \text{ mA}, \text{ VGS}(on) = 5 \text{ V},$ | | 15 | | ns |
| Rise Time | tr | $R_G = 10 \Omega$, $R_L = 500 \Omega$ | | 20 | | ns |
| Turn-Off Delay Time | td(off) | | | 100 | | ns |
| Fall Time | t _f | | | 100 | | ns |

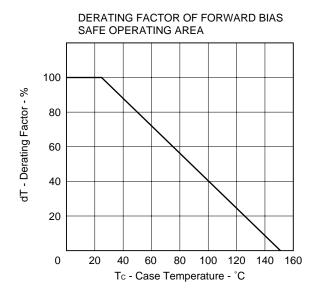
SWITCHING TIME MEASUREMENT CIRCUIT AND CONDITIONS (RESISTANCE LOADED)

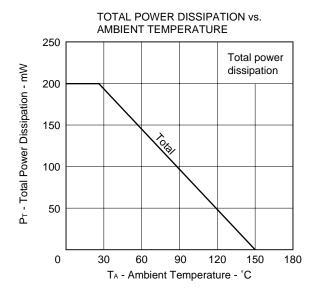


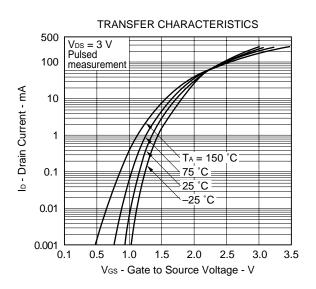


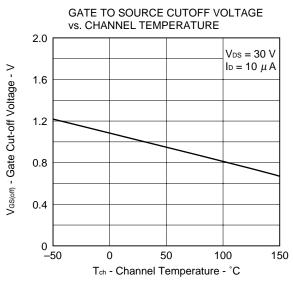
NEC

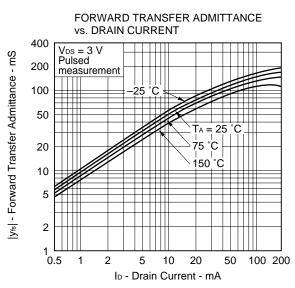
TYPICAL CHARACTERISTICS (TA = 25 °C)

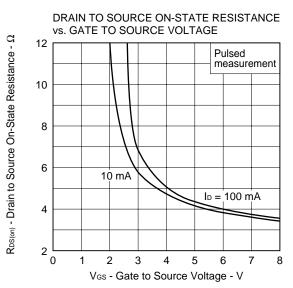




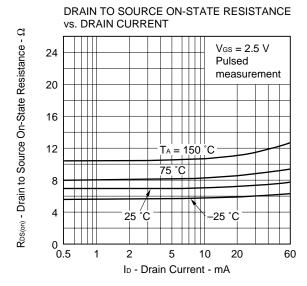


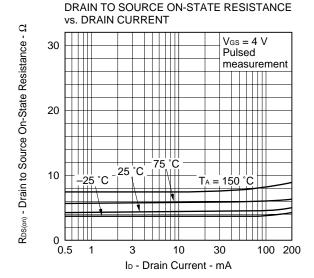


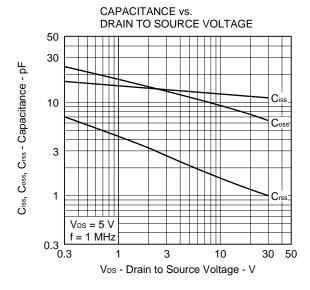


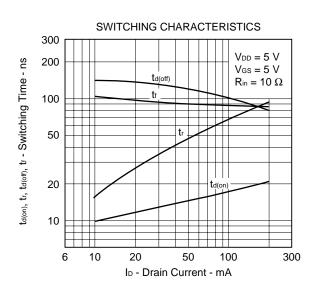


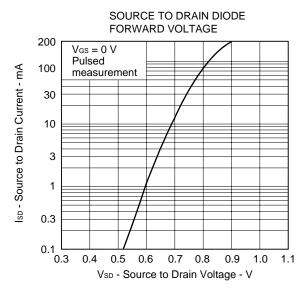


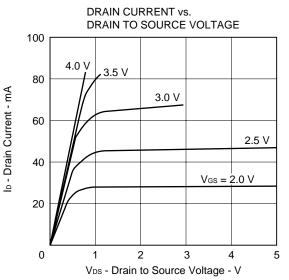














REFERENCE

| Document Name | Document No. | |
|---|--------------|--|
| NEC semiconductor device reliability/quality control system | TEI-1202 | |
| Quality grade on NEC semiconductor devices | IEI-1209 | |
| Semiconductor device mounting technology manual | C10535E | |
| Guide to quality assurance for semiconductor devices | MEI-1202 | |
| Semiconductor selection guide | X10679E | |

NEC μ PA572T

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